What is claimed is:

1. A method for producing an electrical subassembly with a circuit carrier and at least one passive component that is integrated into the circuit carrier and comprises an electrically functional material, the method comprising the following steps:

   structuring the circuit carrier, at least one recess being created for said passive element;

   introducing the electrically functional material in a raw state into the recess of said circuit carrier;

   converting said electrically functional material from said raw state into a final state by supplying energy.

2. The method according to claim 1, wherein energy is supplied by exerting mechanical pressure.

3. The method according to claim 1, wherein energy is supplied by supplying heat.

4. The method according to claim 1, wherein said passive component is a capacitor with a dielectric as an electrically functional material.

5. The method according to claim 1, wherein said passive component is a resistor, said electrically functional material in the raw state being a paste having a given specific resistance.

6. The method according to claim 1, wherein the step of introducing said electrically functional material in the raw state into the recess of said circuit carrier comprises the wiping of a paste.

7. The method according to claim 1, wherein the step of introducing said electrically functional material in the raw state into the recess of said circuit carrier comprises the pressing in of a paste.

8. The method according to claim 1, further comprising the following step:

forming at least one conductor track structure for electrically contacting the electrically functional material.

9. The method according to claim 1, wherein the step of structuring the circuit carrier comprises producing recesses by machining.

10. The method according to claim 1, wherein the step of structuring said circuit carrier comprises:

forming at least one first layer;

forming at least one second layer having openings arranged therein;

joining said first and second layers to obtain said circuit carrier so that said recesses are formed by said openings.

11. The method according to claim 10, wherein said first and second layers are made from ceramics and the step of joining comprises the pressing and firing of said ceramics.

12. The method according to claim 10, wherein said first layer can be made from an electrically insulating material and said second layer is formed by metallization.

13. The method according to claim 12, further comprising the following step:

removing at least part of said second layer for exposing said passive component.